

Surface Mount

Surface Mount PLCC Sockets

Description

Plastic Leaded Chip Carriers (PLCCs) in electronic equipment have created a need for socketing devices to attach to printed wiring board assemblies. Delphi Connection Systems' PLCC sockets provide a cost-effective, upgradeable method of utilizing PLCCs. These low profile 4.45 mm [.175 in.] sockets allow high-density PC board stacking.

Delphi's sockets utilize Surface Mount Technology (SMT) and are available with or without a board polarization feature. This internal polarization feature identifies proper chip carrier orientation.

Molded-in standoffs aid the solder cleaning process. Inspection windows in the base help enable easy socket placement on the PC board and facilitate solder joint repair and inspection. A center pad provides an area for pick-and-place processes.

To help ensure correct removal of devices from sockets, an extraction tool is available. This tool fits all socket sizes and has a plastic handle with heat treated steel blades.

Tool Part Number: PLCC2084

Typical Applications

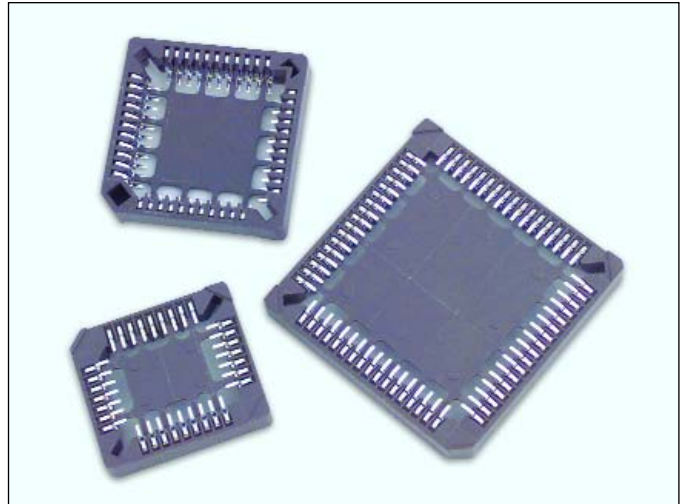
- Computers and peripherals
- Office automation
- Instrumentation

Benefits/Features:

Industry Standard These sockets interface with standard 1.27 mm [.050 in.] pitch PLCCs defined by the JEDEC JC-11 committee and included in JEDEC Publication 95.

Square packages meet the requirements of MS-018.

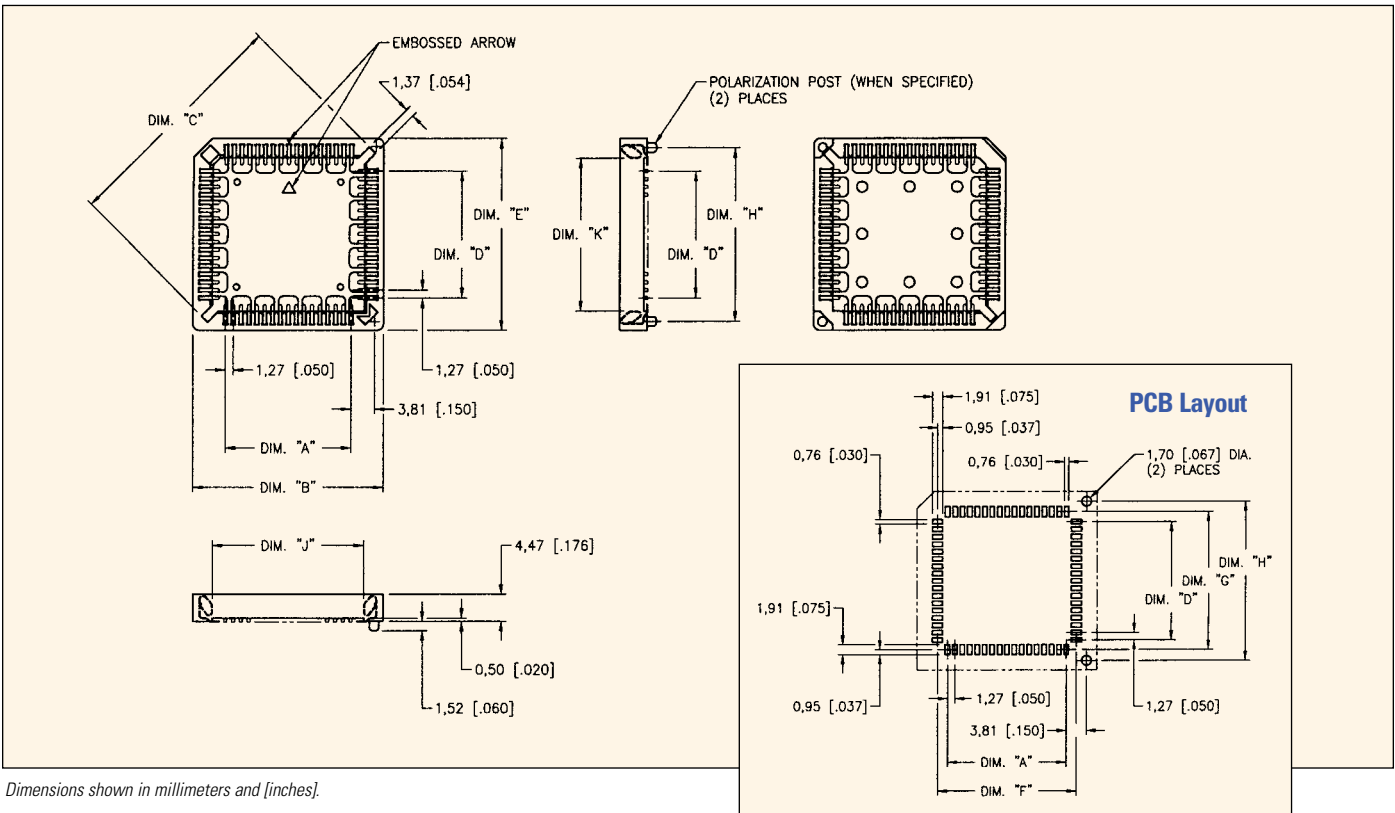
Rectangular packages meet the requirements of MO-052.



Performance Characteristics

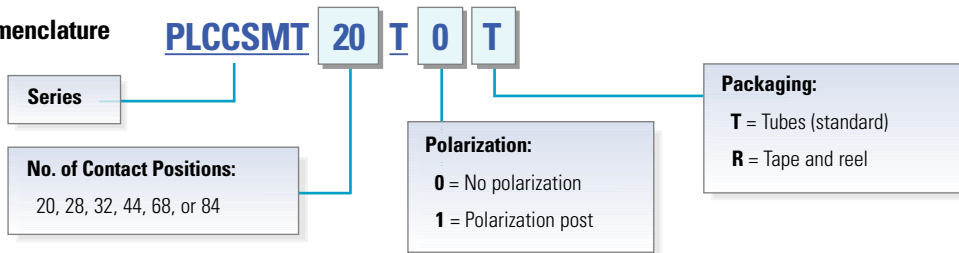
Product Type	Surface mount PLCC sockets
Total No. of Positions	20, 28, 32, 44, 68 and 84
Housing Color	Dark brown
Packaging Type	Tubes (standard) or tape and reel (optional)
Insulator Material	UL94V-0 high temperature thermoplastic Compatible with IR reflow and wave soldering
Current Rating	1.0 amps max. per contact
Contact Resistance	20 mΩ max.
Voltage Rating	120 volts
Continuous Operating Temperature	-55°C to +125°C
Durability (Mating Cycles)	50 cycles
Mating Force	180 grams/pin max.
Unmating Force	28.35 grams/pin min.
Plating (Contact Area)	4.57 μm [180 μin.] tin-lead over nickel underplating
Plating (Soldering End)	4.57 μm [180 μin.] tin-lead over nickel underplating
Underplating	1.14 μm [45 μin.] nickel
Standards, Approvals and Certifications	UL approved: UL File E134099

PLCC Sockets



No. of Positions	Dim. "A"	Dim. "B"	Dim. "C"	Dim. "D"	Dim. "E"	Dim. "F"	Dim. "G"	Dim. "H"	Dim. "J"	Dim. "K"
20	5.08 [.200]	15.24 [.600]	16.70 [.657]	5.08 [.200]	15.24 [.600]	8.48 [.334]	8.48 [.334]	12.70 [.500]	9.40 [.370]	9.40 [.370]
28	7.62 [.300]	17.78 [.700]	20.30 [.799]	7.62 [.300]	17.78 [.700]	11.02 [.434]	11.02 [.434]	15.24 [.600]	11.94 [.470]	11.94 [.470]
32	7.62 [.300]	17.78 [.700]	22.50 [.886]	10.16 [.400]	20.32 [.800]	11.02 [.434]	13.56 [.534]	17.78 [.700]	11.94 [.470]	14.48 [.570]
44	12.70 [.500]	22.86 [.900]	27.50 [1.083]	12.70 [.500]	22.86 [.900]	16.10 [.634]	16.10 [.634]	20.32 [.800]	17.02 [.670]	17.02 [.670]
68	20.32 [.800]	30.82 [1.213]	38.30 [1.508]	20.32 [.800]	30.82 [1.213]	23.72 [.934]	23.72 [.934]	27.94 [1.100]	24.64 [.970]	24.64 [.970]
84	25.40 [1.000]	35.90 [1.413]	45.50 [1.791]	25.40 [1.000]	35.90 [1.413]	28.80 [1.134]	28.80 [1.134]	33.02 [1.300]	29.72 [1.170]	29.72 [1.170]

Ordering Nomenclature



All information is deemed correct as of the date of publication and subject to change without notice. For additional information, please contact Delphi Connection Systems.



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 Printed in the U.S.A.
 DP-03-E-103 503/3W

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